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***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

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In re application of: BAYAN et al.

Attorney Docket No.:  
NSC1P295/P05886

Application No.: 10/789,258

Examiner: DOAN, Theresa T.

Filed: February 26, 2004

Group: 2814

Title: DIE ATTACH PAD FOR USE IN  
SEMICONDUCTOR MANUFACTURING AND  
METHOD OF MAKING SAME

Confirmation No.: 9477

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I hereby certify that this correspondence is being transmitted electronically through EFS-WEB to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 22, 2007.

Signed:   
Sue Funchess

**AMENDMENT D**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Final Office Action dated February 8, 2007, please amend the above-identified patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 6 of this paper.